Title (en)

Method and device for cutting resin film, and cutter used therein

Title (de)

Verfahren und Vorrichtung zum Schneiden von Kunststofffolie und dafür verwendetes Schneidewerkzeug

Title (fr)

Procédé et dispositif de découpe de film en résine, et découpeur utilisé avec celui-ci

Publication

EP 2189259 B1 20120516 (EN)

Application

EP 09014243 A 20091113

Priority

JP 2008296156 A 20081119

Abstract (en)

[origin: EP2189259A1] The Issue of the invention is a resin film (4) laminated on a brittle material plate (3) can be finely cut by a cutter without scratching the surface of the brittle material plate (3) or chipping a cutting edge of the cutter (1a - 1c). A cutter (1a - 1c) is used that includes a lower flat surface (12) perpendicular to an edge line (11) of a cutting edge. The cutter 1a is moved relative to a brittle material plate (3) to cut a resin film (4) with the lower flat surface (12) of the cutter (1a) and the surface of the brittle material plate (3) being in contact with each other. In this configuration, from the viewpoint of finely cutting the resin film (4) and further preventing the surface of the brittle material plate (3) from being scratched, it is preferable that the hardness of the cutting edge of the cutter (1a) be lower than the brittle material plate (3), and higher than the resin film (4).

IPC 8 full level

B26D 1/00 (2006.01); **B26D 1/04** (2006.01); **B26D 3/08** (2006.01)

CPC (source: EP KR)

B26D 1/0006 (2013.01 - EP); **B26D 1/04** (2013.01 - KR); **B26D 1/045** (2013.01 - EP); **B26D 1/12** (2013.01 - KR); **B26D 1/25** (2013.01 - KR); **B26D 3/085** (2013.01 - EP); B26D 2001/006 (2013.01 - EP)

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JP2016078229A; EP2502716A1; CN110092576A; US9339942B2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)

EP 2189259 A1 20100526; **EP 2189259 B1 20120516**; CN 101733768 A 20100616; CN 101733768 B 20120905; CN 102756389 A 20121031; CN 102756389 B 20141217; JP 2010120119 A 20100603; JP 5457014 B2 20140402; KR 101247996 B1 20130327; KR 20100056358 A 20100527; TW 201021987 A 20100616; TW 201302406 A 20130116; TW I421159 B 20140101; TW I451953 B 20140911

DOCDB simple family (application)

EP 09014243 A 20091113; CN 200910176198 A 20090925; CN 201210241637 A 20090925; JP 2008296156 A 20081119; KR 20090081129 A 20090831; TW 101134983 A 20091006; TW 98133868 A 20091006